

[View Auction Brochure](#)[Rigger checkout procedure](#)[View Letter of Guarantee](#)[View Proxy Bid Form](#)[View Agent Release Form](#)[View State Sales Tax Forms](#)[View Terms and Conditions](#)**Ending:** June 1, 2010**On Behalf Of:** Heetronix Corporation**Location:** Reno, Nevada, USA**Public Preview Times:**

On Site Preview of the facility will be held on May 31, 2010, from 9:00am to 5:00pm.

**Key Assets:**

[Sealed bid lot #1. US 6,239,432 B1 IR Radiation Sensing With SiC](#)

[Sealed bid lot #2. US 6,576,972 B1 High Temperature Circuit Structures With Expansion Matched SiC](#)

[Sealed bid lot #3. US 6,649,994 B2 Temperature Sensing System With Matched Temperature Coefficients of Expansion](#)

[Sealed bid lot #4. US 6,713,762 B2 Acoustic Absorption Electromagnetic Radiation Sensing With SiC](#)

[Sealed bid lot #5. US 6,765,278 B2 Circuit Structure with W<sub>1</sub>WC and or W\(2\)C Layer on AlN Die](#)

[Sealed bid lot #6. US 6,765,278 B2 Circuit Structure with W<sub>1</sub>WC and or W\(3\)C Layer on AlN Die](#)

[Sealed bid lot #7. US 6,989,574 B2 High Temperature Circuit Structures With Thin Film Layer \(2\)](#)

[Sealed bid lot #8. US 6,995,691 B2 Bonded Structure Using Reacted Borosilicate Mixture.pdf](#)

[Sealed bid lot #9. US 7,106,167 B2 Stable High Temperature Sensor System With Tungsten on AlN](#)

[Sealed bid lot #10. US 7,176,461 B2 Acoustic Absorption Radiation Sensing in SiC](#)

[Sealed bid lot #11. US 7,190,250 B2 Encapsulation With Oxide Bond To Borosilicate Mixture](#)

[Sealed bid lot #12. US 7,224,256 B2 Stable High Temperature Heater With Serpentine Heating Strands on Insulate Substrate](#)

**Description:**

By order of U.S. Bankruptcy Court Approval Case # NV-09-53112-LBR:

Sealed Bid Sale  
Patents and Intellectual Properties of

Heetronix

Thin Film Silicon Carbide Radiation Sensor  
Manufacturer

**Location:**

725 Trademark Drive #104  
Reno, Nv. 89521

**Auctioneer's Note:**

Heritage Global Partners is pleased to offer the patents of Heetronix Corp for sale by Sealed-Bid Auction. All bid submitted must be in full conformance with the Terms & Conditions of this auction. We encourage prospective bidders to conduct their due diligence and submit their bids no later than the Bid Submission Deadline. Please bear in mind that all bids should be submitted on a "best and final" basis, as there will be no subsequent overbid process nor any opportunity to raise your bids after the the Bid Submission Deadline.

Currency:

USD

Buyer's Premium: 18% / 15% (refer to term 7 in the Auction Terms and Conditions for details)

**Contact:**

For questions of either a scientific or technical nature please refer your questions to Jim Parsons of Heetronix. His email is [jdp@heetronix.com](mailto:jdp@heetronix.com)

For questions regarding the Sealed-Bid Auction bidding process, please contact Doug Berman at [dberman@hgpauction.com](mailto:dberman@hgpauction.com) or 707-245-4417

